IN THE CLAIMS

Please cancel claims 23-36 without prejudice.

Please add new claims 120-133 that follow below.

MARKED UP VERSION OF ENTIRE SET OF PENDING CLAIMS

1-36. (Cancelled)

37. (Previously Presented) A shielded housing formed by the method comprising:

forming a flat pattern of the shielded housing from a sheet of conductive material, the flat pattern including one or more forward fingers extending from an edge thereof;

folding the flat pattern along fold lines to form flaps and sides of the shielded housing; and

bending the flat pattern along bend lines to form the one or more forward fingers of the shielded housing.

38. (Original) A method of assembling an opto-electronic module comprising:

forming a shielded housing with an open end, the shielded housing formed out of a sheet of conductive material to provide electromagnetic radiation shielding and protection of components, the shielded housing including one or more fingers to couple the shielded housing to ground;

assembling optical, electrical and optical-electrical components into a chassis to form a subassembly;

inserting the subassembly into the open end of the shielded housing, the shielded housing around the subassembly; and

closing the open end of the shielded housing to hold the subassembly and the shielded housing assembled together.

39. (Original) The method of claim 38 wherein, the shielding housing is a one-piece shielding housing to protect components and to shield electromagnetic radiation.

40. (Original) The method of claim 38 wherein, the open end is a back side and the inserting includes

inserting a front end of the subassembly into the open end of the back side of the shielded housing.

41. (Original) The method of claim 40 wherein, the closing of the open end of the back side includes

folding a left side wing and a right side wing into the open end, and

folding a back side flap down over the open end to couple to the left side wing and the right side wing.

42. (Original) The method of claim 38 wherein, the open end is a front side and the inserting includes

inserting a rear end of the subassembly into the open end of the front side of the shielded housing.

43. (Previously Presented) The method of claim 42 wherein,

the closing of the open end of the front side includes

folding a strap and a septum of the shielded housing, the strap folded across the open end to strap the subassembly into the shielded housing, the septum folded into the open end to couple to the bottom side of the shielded housing to hold the subassembly strapped into the shielded housing.

44. (Previously Presented) The method of claim 38 wherein,

the forming of the shielded housing includes

stamping a pattern of the shielded housing into the sheet of conductive material, the pattern including the one or more fingers near an edge of the flat sheet,

folding the sheet of conductive material along a plurality of fold lines into a multi-sided rectangularly shaped container but for the open end, and

bending the one or more fingers into shape.

45. (Previously Presented) An opto-electronic module formed by the method comprising:

forming a shielded housing with an open end, the shielded housing formed out of a sheet of conductive material to provide electromagnetic radiation shielding and protection of components, the shielded housing including one or more forward fingers extending from an edge to couple the shielded housing to ground;

assembling optical, electrical and optical-electrical components into a chassis to form a subassembly;

inserting the subassembly into the open end of the shielded housing, the shielded housing around the subassembly; and

closing the open end of the shielded housing to hold the subassembly and the shielded housing assembled together.

46-63. (Cancelled)

64. (Original) A method to assemble an EMI shielding module comprising:

forming a plurality of substantially equidistant spring fingers along an edge of a flat sheet;

forming a strap at the edge of the flat sheet and a septum on the end of the strap;

forming a pair of bottom flaps in the flat sheet;

folding the flat sheet along axes to form a container substantially in the shape of rectangular box, the rectangular box having a first end and a second end, the first end having the plurality of fingers along each of a plurality of edges and an opening for cable connectors, the second end having a backside flap;

folding the strap across the opening for cable connectors; and

coupling the septum to inner surfaces of the bottom flaps to hold the strap across the opening.

65. (Original) The method of claim 64 wherein,

the EMI shielding module is a one-piece shielded housing to protect components and to shield electromagnetic radiation.

66. (Original) The method of claim 64 wherein, the EMI shielding module encloses a module chassis frame, the module chassis frame being a central structural support to which one or more optical, electrical and optical-electrical components used in transmission and reception of optical signals are attached.

67-76. (Cancelled)

77. (Original) A method to assemble an optical transmitter and/or receiver, the method comprising:

forming a plurality of fingers, a strap, and a septum along a first edge of a conductive sheet;

placing the conductive sheet on a module chassis frame, the module chassis frame having a plurality of components used in transmitting and/or receiving optical signals;

folding the conductive sheet around the module chassis frame such that the conductive sheet substantially encloses the module chassis frame but for a frontal opening adjacent to the first edge.

78. (Original) The method of claim 77 further comprising:

bending the strap and the septum around a front end of the module chassis frame to hold the folded conductive sheet and the module chassis frame together.

79. (Original) The method of claim 77 wherein, the fingers to electrically ground the folded conductive sheet to a ground of a host system.

80. (Original) The method of claim 77 wherein, the conductive sheet is one of metal, conductive plastic, and plated plastic.

81. (Original) The method of claim 77 further comprising: bending the plurality of fingers outward from the frontal opening.

82. (Original) The method of claim 77 further comprising: lifting the plurality of fingers up from an outer surface of the conductive sheet.

83-94. (Cancelled)

95. (Previously Presented) The shielded housing of claim 37 wherein, the shielding housing is a one-piece shielded housing to protect components and to shield electromagnetic radiation.

96. (Previously Presented) The shielded housing of claim 37 wherein, prior to the folding and the bending, placing the flat pattern onto a chassis including an opto-electronic device to process optical and electrical signals, and the folding and the bending of the flat pattern is around the chassis to assemble the chassis and the shielded housing together.

97. (Previously Presented) The shielded housing of claim 37 wherein,

the folding and the bending of the flat pattern substantially forms the shielded housing but for a front opening, and

the method further includes

performing final folding and final bending of a strap and a septum to close the front opening.

98. (Previously Presented) The shielded housing of claim 37 wherein,

the folding and the bending of the flat pattern substantially forms the shielded housing but for a rear opening, and

the method further includes

performing final folding and final bending of a back side flap to close the rear opening.

99. (Previously Presented) The shielded housing of claim 37 wherein,

the flat pattern further includes a pair of tangs, a pair of tang window openings, a strap, and a septum.

100. (Previously Presented) The shielded housing of claim 37 wherein,

the folding and the bending forms the shielded housing including

a top side,

a first left side flap including a left wing flap,

a first right side flap including a right wing flap,

a second left side flap including a bottom left side flap,

a second right side flap including a bottom right side flap, and

a back side flap including a retaining flap.

101. (Previously Presented) The shielded housing of claim 100 wherein,

the back side flap includes a pair of tangs,

the left wing flap includes a tang window opening to mate with one of the pairs of tangs, and

the right wing flap includes a tang window opening to mate with one of the pairs of tangs.

102. (Previously Presented) The shielded housing of claim 101 wherein,

a strap extends from a front edge of the top side at one end,

and a septum extends at an opposite end of the strap.

103. (Previously Presented) The shielded housing of claim 100 wherein,

the one or more forward fingers extend from a front edge of the top side, the second left side flap, the second right side flap, the bottom left side flap, and the bottom right side flap.

104. (Previously Presented) The shielded housing of claim 37 wherein,

the one or more forward fingers to couple to a host panel to ground the shielded housing and to seal

around an opening in the host panel to avoid electromagnetic radiation leaking out therefrom.

105. (Previously Presented) The shielded housing of claim 37 wherein,

the flat pattern is formed by etching the sheet of conductive material.

106. (Previously Presented) The shielded housing of claim 37 wherein,

the flat pattern is by formed stamping the sheet of conductive material.

107. (Previously Presented) The shielded housing of claim 37 wherein,

the flat pattern is formed by cutting the sheet of conductive material.

108. (Previously Presented) The opto-electronic module of claim 45 wherein,

the shielding housing is a one-piece shielding housing to protect components and to shield electromagnetic radiation.

109. (Previously Presented) The opto-electronic module of claim 45 wherein,

the open end is a back side and the inserting includes

inserting a front end of the subassembly into the open end of the back side of the shielded housing.

110. (Previously Presented) The opto-electronic module of claim 109 wherein,

the closing of the open end of the back side includes

folding a left side wing and a right side wing into the open end, and

folding a back side flap down over the open end to couple to the left side wing and the right side wing.

111. (Previously Presented) The opto-electronic module of claim 45 wherein,

the open end is a front side and the inserting includes

inserting a rear end of the subassembly into the open end of the front side of the shielded housing.

112. (Previously Presented) The opto-electronic module of claim 111 wherein,

the closing of the open end of the front side includes

folding a strap and a septum of the shielded housing, the strap folded across the open end to strap the subassembly into the shielded housing, the septum folded into the open end to couple to the bottom side of the shielded housing to hold the subassembly strapped into the shielded housing.

113. (Previously Presented) The opto-electronic module of claim 45 wherein,

the forming of the shielded housing includes

stamping a pattern of the shielded housing into the sheet of conductive material, the pattern including the one or more forward fingers extending from the edge of the sheet,

folding the sheet of conductive material along a plurality of fold lines into a multi-sided rectangularly shaped container but for the open end, and

bending the one or more forward fingers into shape.

114. (Previously Presented) An optical transmitter and/or receiver formed by the method comprising:

forming a plurality of fingers, a strap, and a septum along a first edge of a conductive sheet;

placing the conductive sheet on a module chassis frame, the module chassis frame having a plurality of components used in transmitting and/or receiving optical signals;

folding the conductive sheet around the module chassis frame such that the conductive sheet substantially encloses the module chassis frame but for a frontal opening adjacent to the first edge.

115. (Previously Presented) The optical transmitter and/or receiver of claim 114 formed by the method further comprising:

bending the strap and the septum around a front end of the module chassis frame to hold the folded conductive sheet and the module chassis frame together.

116. (Previously Presented) The optical transmitter and/or receiver of claim 114 wherein,

the fingers to electrically ground the folded conductive sheet to a ground of a host system and to seal an opening in a host panel of the host system to avoid electromagnetic radiation leaking out through the opening in the host panel.

117. (Previously Presented) The optical transmitter and/or receiver of claim 114 wherein,

the conductive sheet is one of metal, conductive plastic, and plated plastic.

118. (Previously Presented) The optical transmitter and/or receiver of claim 114 formed by the method further comprising:

bending the plurality of fingers outward from the frontal opening to form a plurality of forward fingers extending out therefrom.

119. (Previously Presented) The optical transmitter and/or receiver of claim 114 formed by the method further comprising:

lifting the plurality of fingers up from an outer surface of the conductive sheet to form a plurality of backward fingers.

120. (New) A method of forming a shielded housing for a fiber-optic module, the method comprising:

forming a flat pattern of the shielded housing from a sheet of conductive material, the flat pattern including one or more fingers;

folding the flat pattern along fold lines to form flaps and sides of the shielded housing; and

bending the flat pattern along bend lines to form the one or more fingers of the shielded housing.

121. (New) The method of claim 120, wherein the shielding housing is a one-piece shielded housing to protect components and to shield electromagnetic radiation.

122. (New) The method of claim 120, wherein prior to the folding and the bending, placing the flat pattern onto a chassis including an opto-electronic device to process optical and electrical signals, and the folding and the bending of the flat pattern is around the chassis to assemble the chassis and the shielded housing together.

123. (New) The method of claim 120, wherein the folding and the bending of the flat pattern substantially forms the shielded housing but for a front opening, and inserting a rear of a chassis including an opto-electronic device to process optical and electrical signals into the front opening in the shielded housing, and performing final folding and final bending to the front opening to assemble the chassis and the shielded housing together.

124. (New) The method of claim 120, wherein the folding and the bending of the flat pattern substantially forms the shielded housing but for a rear opening, and

inserting a front of a chassis including an opto-electronic device to process optical and electrical signals into the rear opening in the shielded housing, and

performing final folding and final bending to the rear opening to assemble the chassis and the shielded housing together.

125. (New) The method of claim 120, wherein the flat pattern further includes a pair of tangs, a pair of tang window openings, a strap, and a septum.

126. (New) The method of claim 120, wherein the folding and the bending forms the shielded housing including

a top side,

a first left side flap including a left wing flap,

a first right side flap including a right wing flap,

a second left side flap including a bottom left side flap,

a second right side flap including a bottom right side flap, and

a back side flap including a retaining flap.

127. (New) The method of claim 126, wherein the back side flap includes a pair of tangs,

the left wing flap includes a tang window opening to mate with one of the pairs of tangs, and

the right wing flap includes a tang window opening to mate with one of the pairs of tangs.

128. (New) The method of claim 127, wherein

a strap extends from a front edge of the top side at one end,

and a septum extends at an opposite end of the strap.

129. (New) The method of claim 126, wherein the one or more fingers extend from a front edge of the top side, the second left side flap, the second right side flap, the bottom left side flap, and the bottom right side flap.

130. (New) The method of claim 126, wherein the one or more fingers extend backward near a front edge from a surface of the top side, the second left side flap, the second right side flap, the bottom left side flap, and the bottom right side flap.

131. (New) The method of claim 126, wherein the forming of the flat pattern is by etching the sheet of conductive material.

132. (New) The method of claim 126, wherein the forming of the flat pattern is by stamping the sheet of conductive material.

133. (New) The method of claim 126, wherein the forming of the flat pattern is by cutting the sheet of conductive material.